

## DS91D176/DS91C176

# 100 MHz Single Channel M-LVDS Transceivers

## **General Description**

The DS91C176 and DS91D176 are 100 MHz single channel M-LVDS (Multipoint Low Voltage Differential Signaling) transceivers designed for applications that utilize multipoint networks (e.g. clock distribution in ATCA and uTCA based systems). M-LVDS is a new bus interface standard (TIA/EIA-899) optimized for multidrop networks. Controlled edge rates, tight input receiver thresholds and increased drive strength are sone of the key enhancments that make M-LVDS devices an ideal choice for distributing signals via multipoint networks.

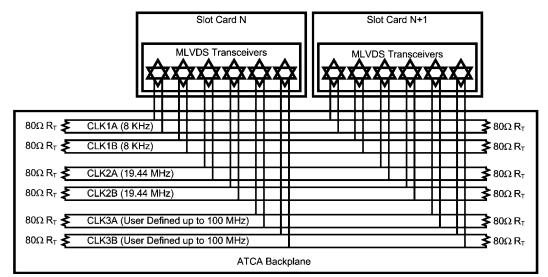
The DS91C176/DS91D176 are half-duplex transceivers that accept LVTTL/LVCMOS signals at the driver inputs and convert them to differential M-LVDS signals. The receiver inputs accept low voltage differential signals (LVDS, B-LVDS, M-LVDS, LV-PECL and CML) and convert them to 3V LVCMOS

signals. The DS91D176 has a M-LVDS type 1 receiver input with no offset. The DS91C176 has an M-LVDS type 2 receiver which enable failsafe functionality.

#### **Features**

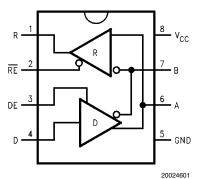
- DC to 100+ MHz / 200+ Mbps low power, low EMI operation
- Optimal for ATCA, uTCA clock distribution networks
- Meets or exceeds TIA/EIA-899 M-LVDS Standard
- Wide Input Common Mode Voltage for Increased Noise Immunity
- DS91D176 has type 1 receiver input
- DS91C176 has type 2 receiver with fail-safe
- Industrial temperature range
- Space saving SOIC-8 package

#### Typical Application in an ATCA Clock Distribution Network



20024630

## **Connection and Logic Diagram**



Top View
Order Number DS91D176TMA, DS91C176TMA
See NS Package Number M08A

## **Ordering Information**

Order Number	Receiver Input	Function	Package Type
DS91D176TMA	type 1	Data (0V threshold receiver)	SOIC/M08A
DS91C176TMA	type 2	Control (100 mV offset fail-safe receiver)	SOIC/M08A

## **M-LVDS Receiver Types**

The EIA/TIA-899 M-LVDS standard specifies two different types of receiver input stages. A type 1 receiver has a conventional threshold that is centered at the midpoint of the input amplitude,  $V_{\rm ID}/2$ . A type 2 receiver has a built in offset that is 100mV greater than  $V_{\rm ID}/2$ . The type 2 receiver offset acts as a failsafe circuit where open or short circuits at the input will always result in the output stage being driven to a low logic state.

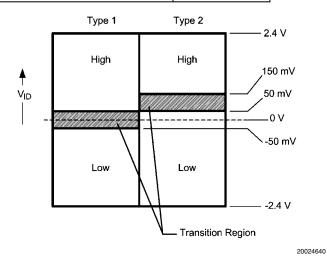


FIGURE 1. M-LVDS Receiver Input Thresholds

#### **Absolute Maximum Ratings** (Note 1)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/ Distributors for availability and specifications.

Maximum Package Power Dissipation at +25°C

SOIC Package 833 mW

Derate SOIC Package 6.67 mW/°C above +25°C

Thermal Resistance (4-Layer, 2 oz. Cu, JEDEC)

 $\begin{array}{ccc} \theta_{JA} & 150^{\circ}\text{C/W} \\ \theta_{JC} & 63^{\circ}\text{C/W} \\ \text{Maximum Junction Temperature} & 150^{\circ}\text{C} \\ \text{Storage Temperature Range} & -65^{\circ}\text{C to } +150^{\circ}\text{C} \end{array}$ 

(Soldering, 4 seconds) 260°C ESD Ratings: (HBM 1.5k $\Omega$ , 100pF)  $\geq$  8 kV (EIAJ 0 $\Omega$ , 200pF)  $\geq$  250 V (CDM 0 $\Omega$ , 0pF)  $\geq$  1000 V

# Recommended Operating Conditions

Lead Temperature

	Min	Тур	Max	Units
Supply Voltage, $V_{CC}$	3.0	3.3	3.6	V
Voltage at Any Bus Terr	minal -1.4		+3.8	V
(Separate or Commor	n-Mode)			
Differential Input Voltage	e V <sub>ID</sub>		2.4	V
LVTTL Input Voltage High	gh V <sub>IH</sub> 2.0		$V_{CC}$	V
LVTTL Input Voltage Lo	w V <sub>IL</sub> 0		0.8	V
Operating Free Air				
Temperature T <sub>A</sub>	-40	+25	+85	°C

#### **Electrical Characteristics**

Over recommended operating supply and temperature ranges unless otherwise specified. (Note 2, Note 3, Note 4, Note 8)

Symbol	Parameter	Conditions		Min	Тур	Max	Units
M-LVDS D	river						
IV <sub>AB</sub> I	Differential output voltage magnitude	$R_L = 50\Omega$ , $C_L = 5pF$		480		650	mV
$\Delta V_{AB}$	Change in differential output voltage magnitude between logic states	Figure 2 and Figure 4		-50	0	+50	mV
V <sub>OS(SS)</sub>	Steady-state common-mode output voltage	$R_L = 50\Omega$ , $C_L = 5pF$		0.3	1.8	2.1	٧
$ \Delta V_{OS(SS)} $	Change in steady-state common-mode output voltage between logic states	Figure 2 and Figure 3		0		+50	mV
V <sub>OS(PP)</sub>	Peak-to-peak common-mode output voltage	(V <sub>OS(PP)</sub> @ 500KHz clock)			135		mV
V <sub>A(OC)</sub>	Maximum steady-state open-circuit output voltage	Figure 5		0		2.4	٧
V <sub>B(OC)</sub>	Maximum steady-state open-circuit output voltage	1		0		2.4	٧
V <sub>P(H)</sub>	Voltage overshoot, low-to-high level output	$R_1 = 50\Omega$ , $C_1 = 5pF$ , $C_D = 0.5pF$				1.2V <sub>SS</sub>	٧
V <sub>P(L)</sub>	Voltage overshoot, high-to-low level output	Figure 7 and Figure 8 (Note 9)		-0.2V <sub>S</sub>			٧
				s			v
I <sub>IH</sub>	High-level input current (LVTTL inputs)	V <sub>IH</sub> = 2.0V		-15		15	μΑ
$I_{\rm IL}$	Low-level input current (LVTTL inputs)	$V_{IL} = 0.8V$		-15		15	μΑ
V <sub>IKL</sub>	Input Clamp Voltage (LVTTL inputs)	I <sub>IN</sub> = -18mA		-1.5			٧
I <sub>os</sub>	Differential short-circuit output current	Figure 6		-43		43	mA
M-LVDS R	eceiver					_	
$V_{IT+}$	Positive-going differential input voltage threshold	See Function Tables	Type 1		20	50	mV
			Type 2		94	150	mV
$V_{IT-}$	Negative-going differential input voltage threshold	See Function Tables	Type 1	-50	20		mV
			Type 2	50	94		mV
$V_{OH}$	High-level output voltage (LVTTL output)	$I_{OH} = -8mA$		2.4	2.7		V
$V_{OL}$	Low-level output voltage (LVTTL output)	I <sub>OL</sub> = 8mA			0.28	0.4	>
$I_{OZ}$	TRI-STATE output current	V <sub>O</sub> = 0V or 3.6V		-10		10	μΑ
I <sub>OSR</sub>	Short-circuit receiver output current (LVTTL output)	) V <sub>O</sub> = 0V			-48	-90	mA
M-LVDS B	us (Input and Output) Pins						
I <sub>A</sub>	Transceiver input/output current	$V_A = 3.8V, V_B = 1.2V$				32	μΑ
		$V_A = 0V \text{ or } 2.4V, V_B = 1.2V$	<b>/</b>	-20		+20	μΑ
		$V_A = -1.4V, V_B = 1.2V$		-32			μA

Symbol	Parameter	Conditions	Min	Тур	Max	Units
I <sub>B</sub>	Transceiver input/output current	$V_B = 3.8V, V_A = 1.2V$			32	μΑ
		V <sub>B</sub> = 0V or 2.4V, V <sub>A</sub> = 1.2V	-20		+20	μΑ
		$V_B = -1.4V, V_A = 1.2V$	-32			μA
I <sub>AB</sub>	Transceiver input/output differential current $(I_A - I_B)$	$V_A = V_B, -1.4V \le V \le 3.8V$	-4		+4	μΑ
I <sub>A(OFF)</sub>	Transceiver input/output power-off current	$V_A = 3.8V$ , $V_B = 1.2V$ , $DE = V_{CC}$ $0V \le V_{CC} \le 1.5V$			32	μА
		$V_A = 0V \text{ or } 2.4V, V_B = 1.2V,$ $DE = V_{CC}$ $0V \le V_{CC} \le 1.5V$	-20		+20	μА
		$V_A = -1.4V$ , $V_B = 1.2V$ , $DE = V_{CC}$ $0V \le V_{CC} \le 1.5V$	-32			μА
I <sub>B(OFF)</sub>	Transceiver input/output power-off current	$V_B = 3.8V$ , $V_A = 1.2V$ , $DE = V_{CC}$ $0V \le V_{CC} \le 1.5V$			32	μА
		$V_B = 0V \text{ or } 2.4V, V_A = 1.2V,$ $DE = V_{CC}$ $0V \le V_{CC} \le 1.5V$	-20		+20	μА
		$V_B = -1.4V$ , $V_A = 1.2V$ , $DE = V_{CC}$ $0V \le V_{CC} \le 1.5V$	-32			μА
I <sub>AB(OFF)</sub>	Transceiver input/output power-off differential current $(I_{A(OFF)} - I_{B(OFF)})$	$V_A = V_B$ , $-1.4V \le V \le 3.8V$ , $DE = V_{CC}$ $0V \le V_{CC} \le 1.5V$	-4		+4	μА
C <sub>A</sub>	Transceiver input/output capacitance	V <sub>CC</sub> = OPEN		9		pF
C <sub>B</sub>	Transceiver input/output capacitance			9		pF
C <sub>AB</sub>	Transceiver input/output differential capacitance			5.7		pF
C <sub>A/B</sub>	Transceiver input/output capacitance balance $(C_A/C_B)$			1.0		
SUPPLY C	CURRENT (V <sub>CC</sub> )					
I <sub>CCD</sub>	Driver Supply Current	$R_{L} = 50\Omega$ , $DE = V_{CC}$ , $\overline{RE} = V_{CC}$		20	29.5	mA
I <sub>CCZ</sub>	TRI-STATE Supply Current	$DE = GND, \overline{RE} = V_{CC}$		6	9.0	mA
I <sub>CCR</sub>	Receiver Supply Current	DE = GND, RE = GND		14	18.5	mA

## **Switching Characteristics**

Over recommended operating supply and temperature ranges unless otherwise specified. (Note 3, Note 8)

Symbol	Parameter	Conditions	Min	Тур	Max	Units
DRIVER AC S	SPECIFICATION			•		
t <sub>PLH</sub>	Differential Propagation Delay Low to High	$R_{L} = 50\Omega, C_{L} = 5 pF,$	1.3	3.4	5.0	ns
t <sub>PHL</sub>	Differential Propagation Delay High to Low	C <sub>D</sub> = 0.5 pF	1.3	3.1	5.0	ns
t <sub>SKD1</sub> (t <sub>sk(p)</sub> )	Pulse Skew It <sub>PLHD</sub> – t <sub>PHLD</sub> I ( <i>Note 5, Note 9</i> )	Figure 7 and Figure 8		300	420	ps
t <sub>SKD3</sub>	Part-to-Part Skew (Note 6, Note 9)				1.3	ns
t <sub>TLH</sub> (t <sub>r</sub> )	Rise Time (Note 9)		1.0	1.8	3.0	ns
t <sub>THL</sub> (t <sub>f</sub> )	Fall Time (Note 9)	7	1.0	1.8	3.0	ns
t <sub>PZH</sub>	Enable Time (Z to Active High)	$R_L = 50\Omega, C_L = 5 pF,$			8	ns
t <sub>PZL</sub>	Enable Time (Z to Active Low)	C <sub>D</sub> = 0.5 pF			8	ns
t <sub>PLZ</sub>	Disable Time (Active Low to Z)	Figure 9 and Figure 10			8	ns
t <sub>PHZ</sub>	Disable Time (Active High to Z)	7			8	ns
t <sub>JIT</sub>	Random Jitter, RJ (Note 9)	100 MHz Clock Pattern (Note 7)		2.5	5.5	psrms
f <sub>MAX</sub>	Maximum Data Rate		200			Mbps
	C SPECIFICATION				!	
t <sub>PLH</sub>	Propagation Delay Low to High	C <sub>L</sub> = 15 pF	2.0	4.7	7.5	ns
t <sub>PHL</sub>	Propagation Delay High to Low	Figures 11, 12 and Figure 13	2.0	5.3	7.5	ns
$t_{SKD1} (t_{sk(p)})$	Pulse Skew It <sub>PLHD</sub> – t <sub>PHLD</sub> I ( <i>Note 5, Note 9</i> )			0.6	1.7	ns
t <sub>SKD3</sub>	Part-to-Part Skew (Note 6, Note 9)				1.3	ns
t <sub>TLH</sub> (t <sub>r</sub> )	Rise Time (Note 9)		0.5	1.2	2.5	ns
t <sub>THL</sub> (t <sub>f</sub> )	Fall Time (Note 9)		0.5	1.2	2.5	ns
t <sub>PZH</sub>	Enable Time (Z to Active High)	$R_L = 500\Omega, C_L = 15 \text{ pF}$			10	ns
t <sub>PZL</sub>	Enable Time (Z to Active Low)	Figure 14 and Figure 15			10	ns
t <sub>PLZ</sub>	Disable Time (Active Low to Z)	1			10	ns
t <sub>PHZ</sub>	Disable Time (Active High to Z)	1			10	ns
f <sub>MAX</sub>	Maximum Data Rate		200			Mbps

**Note 1:** "Absolute Maximum Ratings" are those beyond which the safety of the device cannot be guaranteed. They are not meant to imply that the device should be operated at these limits. The tables of "Electrical Characteristics" provide conditions for actual device operation.

Note 2: All currents into device pins are positive; all currents out of device pins are negative. All voltages are referenced to device ground unless otherwise specified.

Note 3: All typicals are given for  $V_{CC} = 3.3V$  and  $T_A = 25$ °C.

Note 4: The algebraic convention, in which the least positive (most negative) limit is designated as minimum, is used in this datasheet.

Note 5:  $t_{SKD1}$ ,  $|t_{PLHD} - t_{PHLD}|$ , is the magnitude difference in differential propagation delay time between the positive going edge and the negative going edge of the same channel.

Note 6: t<sub>SKD3</sub>, Part-to-Part Skew, is defined as the difference between the minimum and maximum specified differential propagation delays. This specification applies to devices at the same V<sub>CC</sub> and within 5°C of each other within the operating temperature range.

Note 7: Stimulus and fixture Jitter has been subtracted.

Note 8:  $C_L$  includes fixture capacitance and  $C_D$  includes probe capacitance.

Note 9: Not production tested. Guaranteed by a statistical analysis on a sample basis at the time of characterization.

# **Test Circuits and Waveforms**

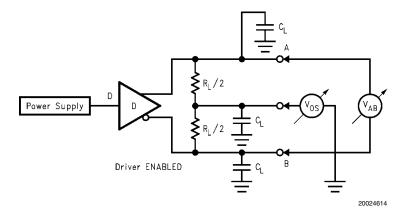


FIGURE 2. Differential Driver Test Circuit

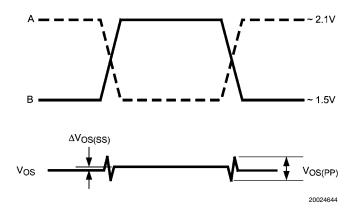


FIGURE 3. Differential Driver Waveforms

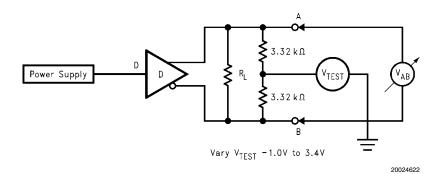


FIGURE 4. Differential Driver Full Load Test Circuit

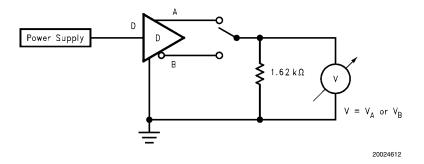


FIGURE 5. Differential Driver DC Open Test Circuit

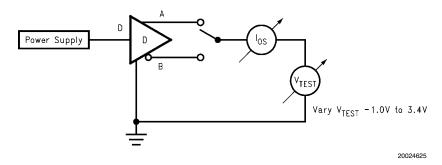


FIGURE 6. Differential Driver Short-Circuit Test Circuit

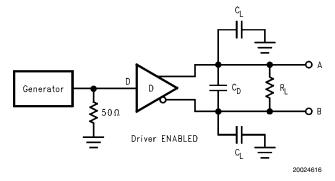


FIGURE 7. Driver Propagation Delay and Transition Time Test Circuit

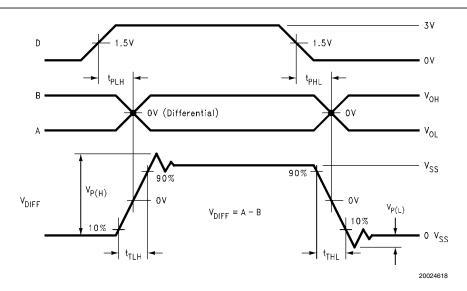


FIGURE 8. Driver Propagation Delays and Transition Time Waveforms

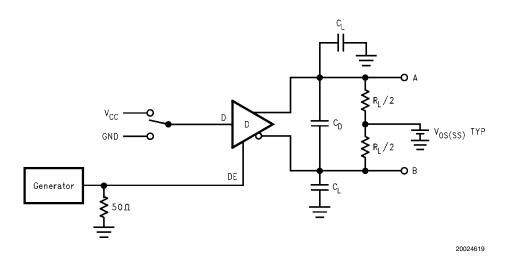


FIGURE 9. Driver TRI-STATE Delay Test Circuit

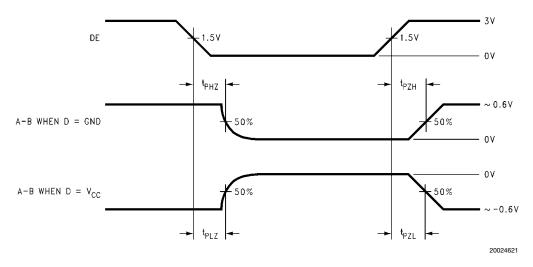


FIGURE 10. Driver TRI-STATE Delay Waveforms

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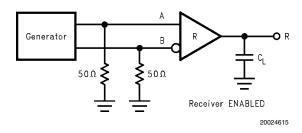


FIGURE 11. Receiver Propagation Delay and Transition Time Test Circuit

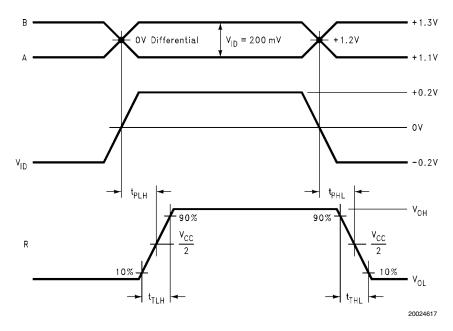


FIGURE 12. Type 1 Receiver Propagation Delay and Transition Time Waveforms

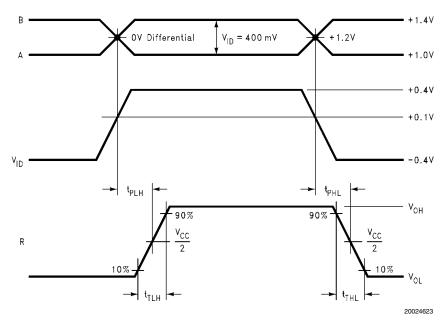


FIGURE 13. Type 2 Receiver Propagation Delay and Transition Time Waveforms

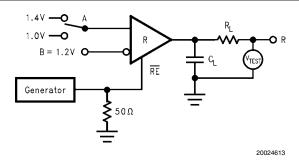


FIGURE 14. Receiver TRI-STATE Delay Test Circuit

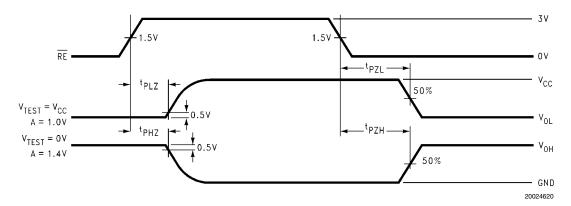


FIGURE 15. Receiver TRI-STATE Delay Waveforms

## **Function Tables**

#### DS91D176/DS91C176 Transmitting

Inputs			Out	puts
RE	DE	D	В	Α
Х	2.0V	2.0V	L	Н
X	2.0V	0.8V	Н	L
X	0.8V	Х	Z	Z

X — Don't care condition

Z — High impedance state

#### DS91D176 Receiving

	Inputs				
RE	DE	A – B	R		
0.8V	0.8V	≥ +0.05V	Н		
0.8V	0.8V	≤ -0.05V	L		
0.8V	0.8V	0V	Χ		
2.0V	0.8V	Х	Z		

X — Don't care condition

Z — High impedance state

#### DS91C176 Receiving

	Inputs				
RE	DE	A – B	R		
0.8V	0.8V	≥ +0.15V	Н		
0.8V	0.8V	≤ +0.05V	L		
0.8V	0.8V	0V	L		
2.0V	0.8V	Х	Z		

X — Don't care condition

Z — High impedance state

#### **DS91D176 Receiver Input Threshold Test Voltages**

Applied	Voltages	Resulting Differential Input Voltage	Resulting Common-Mode Input Voltage	Receiver Output
V <sub>IA</sub>	V <sub>IB</sub>	V <sub>ID</sub>	V <sub>IC</sub>	R
2.400V	0.000V	2.400V	1.200V	Н
0.000V	2.400V	-2.400V	1.200V	L
3.800V	3.750V	0.050V	3.775V	Н
3.750V	3.800V	-0.050V	3.775V	L
-1.400V	-1.350V	-0.050V	-1.375V	Н
-1.350V	-1.400V	0.050V	-1.375V	L

H — High Level L — Low Level

Output state assumes that the receiver is enabled  $(\overline{RE} = L)$ 

#### **DS91C176 Receiver Input Threshold Test Voltages**

Applied Voltages		Resulting Differential Input Voltage	Resulting Common-Mode Input Voltage	Receiver Output
V <sub>IA</sub>	V <sub>IB</sub>	V <sub>ID</sub>	V <sub>IC</sub>	R
2.400V	0.000V	2.400V	1.200V	Н
0.000V	2.400V	-2.400V	1.200V	L
3.800V	3.650V	0.150V	3.725V	Н
3.800V	3.750V	0.050V	3.775V	L
-1.250V	-1.400V	0.150V	-1.325V	Н
-1.350V	-1.400V	0.050V	-1.375V	L

H — High Level

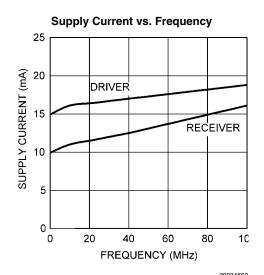
L — Low Level

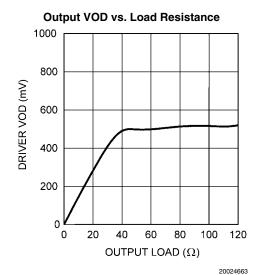
Output state assumes that the receiver is enabled  $(\overline{RE} = L)$ 

# **Pin Descriptions**

Pin No.	Name	Description
1	R	Receiver output pin
2	RE	Receiver enable pin: When $\overline{RE}$ is high, the receiver is disabled. When $\overline{RE}$ is low or open, the receiver is enabled.
3	DE	Driver enable pin: When DE is low, the driver is disabled. When DE is high, the driver is enabled.
4	D	Driver input pin
5	GND	Ground pin
6	Α	Non-inverting driver output pin/Non-inverting receiver input pin
7	В	Inverting driver output pin/Inverting receiver input pin
8	V <sub>CC</sub>	Power supply pin, +3.3V ± 0.3V

# **Typical Performance Characteristics**

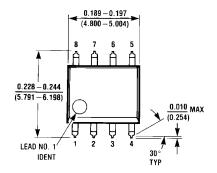


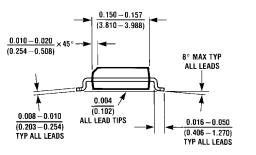


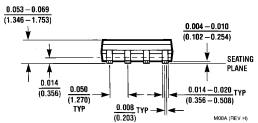
Supply Current measured using a clock pattern with driver terminated to 50 ohms .V $_{CC}$  = 3.3V, T $_{A}$  = +25°C V $_{CC}$  = 3.3V, T $_{A}$  = +25°C.

FIGURE 16. DS91D176/DS91C176 Typical Performance Characteristics

## Physical Dimensions inches (millimeters) unless otherwise noted







Order Number DS91D176TMA, DS91C176TMA See NS package Number M08A

## **Notes**

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Data Converters	www.national.com/adc	Samples	www.national.com/samples	
Interface	www.national.com/interface	Eval Boards	www.national.com/evalboards	
LVDS	www.national.com/lvds	Packaging	www.national.com/packaging	
Power Management	www.national.com/power	Green Compliance	www.national.com/quality/green	
Switching Regulators	www.national.com/switchers	Distributors	www.national.com/contacts	
LDOs	www.national.com/ldo	Quality and Reliability	www.national.com/quality	
LED Lighting	www.national.com/led	Feedback/Support	www.national.com/feedback	
Voltage Reference	www.national.com/vref	Design Made Easy	www.national.com/easy	
PowerWise® Solutions	www.national.com/powerwise	Solutions	www.national.com/solutions	
Serial Digital Interface (SDI)	www.national.com/sdi	Mil/Aero	www.national.com/milaero	
Temperature Sensors	www.national.com/tempsensors	SolarMagic™	www.national.com/solarmagic	
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